

Patent Abstracts of Japan

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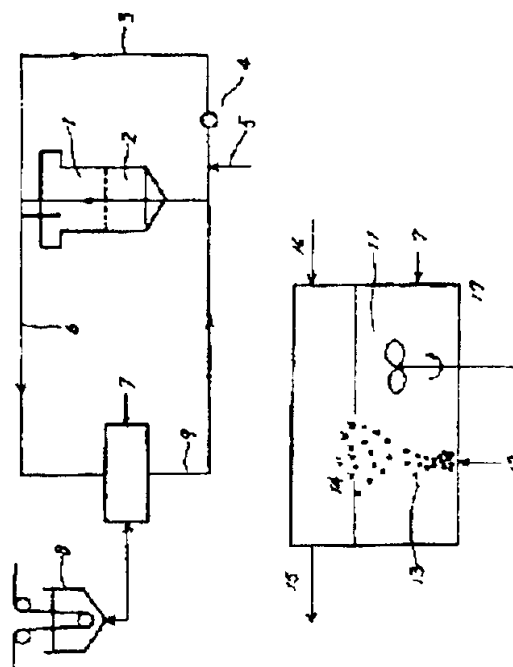
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TITLE : TIN ELECTROPLATING METHOD



ABSTRACT : PURPOSE: To prevent tin ion in a plating soln. from sludging due to oxidation by blowing an inert gas into the plating soln. to be introduced into a plating cell using an insoluble anode from a metallic tin dissolving tank to reduce the dissolved oxygen concn.

CONSTITUTION: A plating soln. 11 is introduced into a dissolving tank 1 packed with a granular metallic tin 2 by a circulating line 3 and a pump, and oxygen necessary for dissolution is blown into the soln. from a device 5. The plating soln. having a high content of tin ion and contg. unreacted dissolved oxygen is introduced into a plating soln. circulating tank 7 through a tin ion supply line 6, the concn. is adjusted to a requisite value, and the soln. is sent to a plating cell 8 to carry out plating. The soln. 11 with the tin ion concn. reduced by the plating is returned to the tank 1 through a return line 9. At this time, the excess dissolved oxygen contained in the soln. 11 sent to the circulating tank 7 from the tank 1 is adsorbed by the bubbles 13 of an inert gas ( $N_2$ , etc.) blown from a device 12 and discharged from an exhaustor 15 by a purging device 16.

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